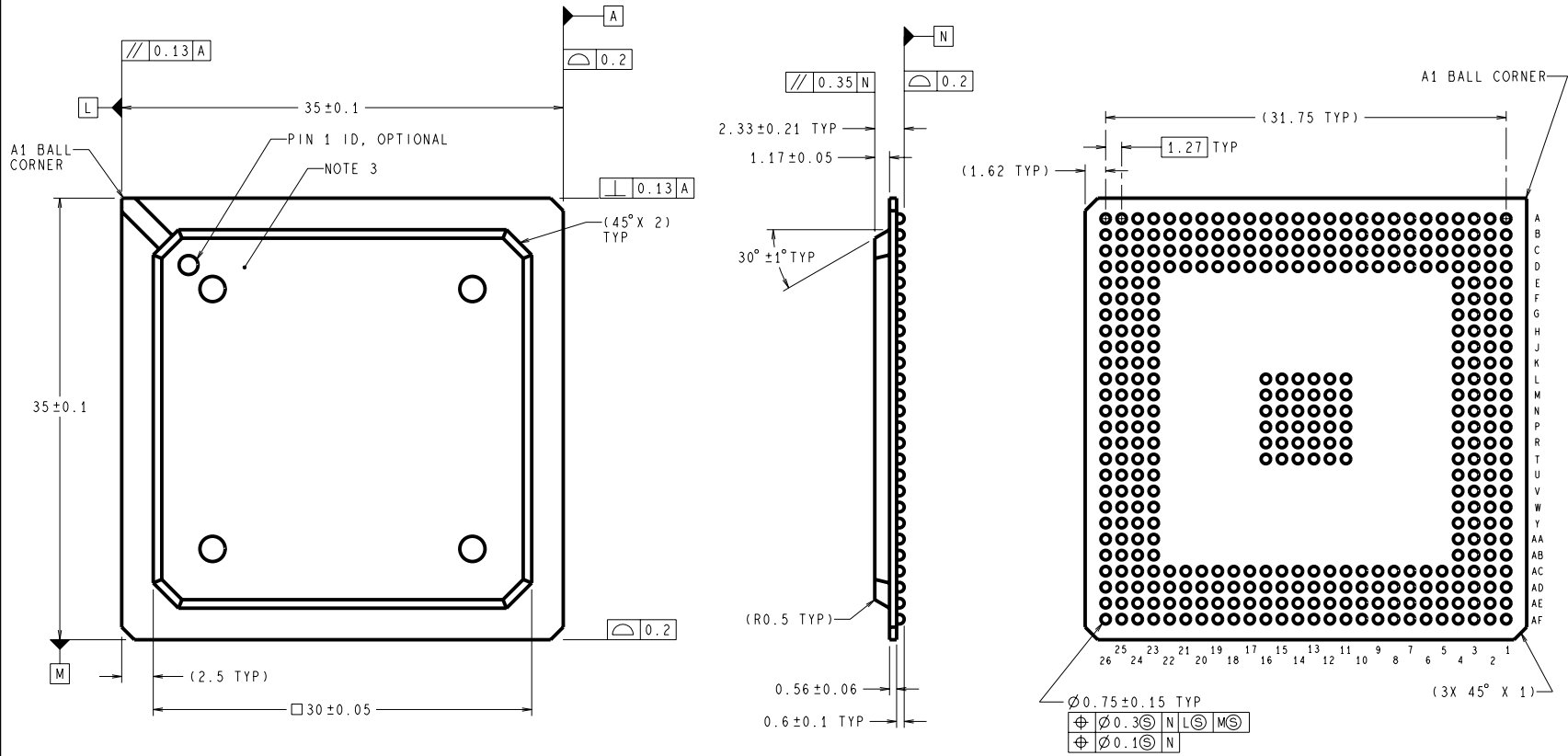


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11633	12/20/1996	TL/SM
B	REVISE SUBSTR CORNERS, BODY CHAMFERS & TOL; ADD EJECTOR PINS TO BODY	11708	10/02/1997	TL/SL
C	REVISE DWG PER MARKUP INPUT.	11934	02/12/1998	MS/



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
2. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
3. THE MOLD SURFACE AREA MAY INCLUDE DIMPLE FOR A1 BALL CORNER IDENTIFICATION.
4. REFERENCE JEDEC REGISTRATION MO-151, VARIATION -1.27 PITCH, DATED FEB. 1996.

APPROVALS		DATE	National Semiconductor		
DRAWN T. LEQUANG		12/20/1996	2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DFTG. CHK.			PBGA, 35 X 35 X 2.33mm, 388 BALL, 1.27mm PITCH		
ENGR. CHK.					
		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(ISC)MKT-UCB388A	C
		DO NOT SCALE DRAWING		SHEET 1 of 1	